

MEG00-001C
Serial number 09/684,519

GP2841



TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)
28 Davis Avenue
Poughkeepsie, NY 12603

Date: April 15, 2003

REF: APPLICANT : Jin-Yuan Lee
~~SERIAL NO.~~ : 09/684,519
~~ART UNIT~~ : 2841
~~FILING DATE~~ : 10/10/00
~~ATT'Y NO.~~ : MEG00-001C
~~EXAMINER~~ : Bui, Hung S.
TITLE : A THERMALLY COMPLIANT PCB
SUBSTRATE FOR THE APPLICATION
OF CHIP SCALE PACKAGES.

AMENDMENT AND RESPONSE TO OFFICE ACTION

Sir:

In response to an office action mailed on 03/34/03
please consider the following amendments and remarks with
respect to the above referenced application.

RECEIVED
JUN -7 2003
TECHNOLOGY CENTER 2000
6/30/03

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal service as First
Class mail in an envelop addressed to the Commissioner of
Patents and Trademarks, Washington, D.C. 20231, on
June 30, 2003,

Stephen B. Ackerman (Reg. No 37,761)

Signature

6/30/03

Date